Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	05/17/2022

Details for "SN65LBC172ADWR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN65LBC172ADWR	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	DW 20	7.52x12.82x2.35	566.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000356	4	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000356	4	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000002	0.000712	7	0	0
Precious Metals	Gold	7440-57-5	0.280967	99.997509	999975	0.049617	496
Precious Metals	Silver	7440-22-4	0.000003	0.001068	11	0.000001	0
Sub-Total			0.280974	100	1000000	0.049618	496
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.087753	69.999994	700000	0.192091	1921
Thermoplastics	Ероху	85954-11-6	0.46618	30.000006	300000	0.082325	823
Sub-Total			1.553933	100	1000000	0.274416	2744
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	145.72536	97.41	974100	25.734278	257343
Copper and Its Alloys	Iron	7439-89-6	3.5904	2.4	24000	0.634044	6340
Copper and Its Alloys	Phosphorus	7723-14-0	0.04488	0.03	300	0.007926	
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.04488	0.03	300	0.007926	
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.04488	0.03	300	0.007926	79
Zinc and Its Alloys	Zinc	7440-66-6	0.1496	0.1	1000	0.026419	264
Sub-Total			149.6	100	1000000	26.418518	264185
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	2.561582	95.120015	951200	0.452361	4524
Precious Metals	Gold	7440-57-5	0.021005	0.779985	7800	0.003709	37
Precious Metals	Palladium	7440-05-3	0.110413	4.1	41000	0.019498	195
Sub-Total			2.693	100	1000000	0.475569	4756
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	308.337157	76	760000	54.450606	544506
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	14.199738	3.5	35000	2.507594	25076
Other Plastics and Rubber	Carbon Black	1333-86-4	1.21712	0.3	3000	0.214937	2149
Thermoplastics	Epoxy	85954-11-6	81.952771	20.2	202000	14.472398	144724
Sub-Total			405.706786	100	1000000	71.645534	716455
Semiconductor Device	·				•	•	
Ceramics / Glass	Doped Silicon	7440-21-3	6.434777	100	1000000	1.136345	11363
Sub-Total			6.434777	100	1000000	1.136345	11363
Total			566.26947			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is." For additional information, presse contact TL customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/17/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CJ) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.